



SAL1 SERIES

(1.00 mm) .0394"

HIGH-SPEED THROUGH BOARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SAL1

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Au or Sn over

50 μ m (1.27 μ m) Ni

Operating Temp:

-55 °C to +125 °C

Current Rating:

2.9 A per pin

(2 adjacent pins powered)

RoHS Compliant: Yes

Mates with:

(1.60 mm) .062" or

(2.36 mm) .093" card

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max

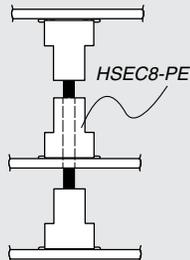
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

OTHER SOLUTIONS



- Card pass-through option. See HSEC8-PE Series.

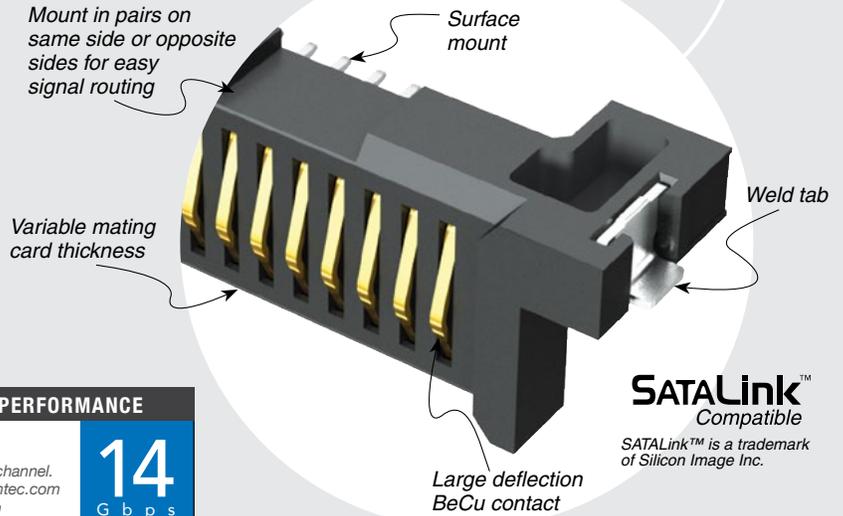
ALSO AVAILABLE (MOQ Required)

- Heavy Gold plating Contact Samtec.

Notes:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications. Contact Samtec for further information.

Some lengths, styles and options are non-standard, non-returnable.



HIGH-SPEED CHANNEL PERFORMANCE

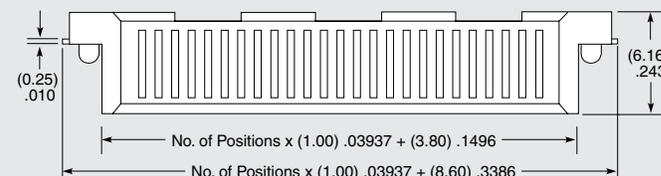
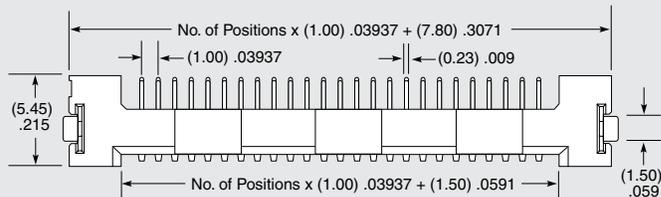
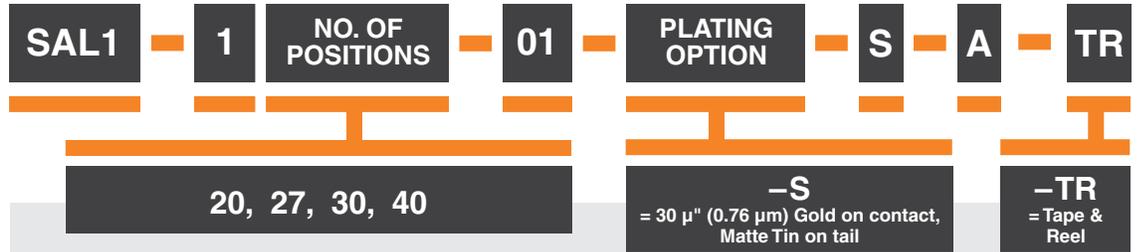
SAL1 (Top Entry)

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

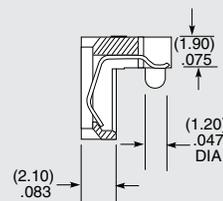
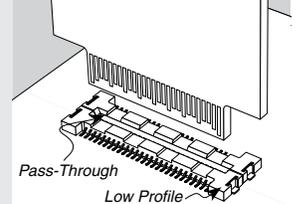
14
Gbps

SATALink™
Compatible

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APPLICATIONS



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.